

IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Withdrawn) A method for manufacturing a display device comprising the steps of:

forming one or a plurality of layers of a conductive pattern over a substrate having an insulating surface;

forming a conductor pillar comprising a same type conductor as or a different type conductor from the conductive pattern;

forming one or a plurality of layers of an insulating film over an entire surface of the substrate;

etching the insulating film back to expose the conductor pillar; and

forming wirings or a conductor pattern for electrically connecting to the conductor pillar by ink jetting.
2. (Withdrawn) A method for manufacturing a display device according to claim 1, wherein the conductor pillar is formed by forming a conductive film over an entire surface, and then, forming a resist pattern by ink jetting, and thereafter, performing anisotropic etching by using the resist pattern as a mask.
3. (Withdrawn) A method for manufacturing a display device according to claim 1, wherein the conductor pillar is formed by locally forming a conductive layer by ink jetting, and then, forming a fine resist pattern by ink jetting, and thereafter, performing anisotropic etching by using the resist

pattern as a mask.

4. (Withdrawn) A method for manufacturing a display device according to claim 1, wherein a conductive layer forming the conductor pillar is locally formed by ink jetting under reduced pressure.

5. (Withdrawn) A method for manufacturing a display device according to claim 1, wherein at least one layer of an insulating film is formed by forming a transparent insulating film by a coating method in a step of depositing the insulating film after forming the pillar.

6. (Withdrawn) A method of manufacturing a display device comprising:
forming a conductive pattern over a substrate having an insulating surface;
forming a conductive pillar on the conductive pattern;
forming an insulating film over the substrate so as to cover the conductive pillar and the conductive pattern;
etching back the insulating film to expose an upper surface of the conductive pillar; and
forming a wiring on the insulating film wherein the wiring contacts the upper surface of the conductive pillar.

7. (Currently Amended) A method of manufacturing a display device comprising:
forming a first wiring over a substrate having an insulating surface;
forming a conductive film over the substrate so as to cover the first wiring;
forming a resist-pattern on the conductive film by ink jetting;

etching the conductive film by using the resist-pattern as a mask to form a conductive pillar on the conductive pattern;

forming an insulating film over the substrate so as to cover the conductive pillar and first wiring;

etching back the insulating film to expose an upper surface of the conductive pillar; and

forming a second wiring on the insulating film wherein the second wiring contacts the upper surface of the conductive pillar so that the first wiring is electrically connected to the second wiring through the conductive pillar.

8. (Original) The method according to 7 wherein the step of etching back the insulating film is performed by anisotropic etching.

9-12. (Canceled)

13. (New) The method according to claim 7 wherein said pattern is made of a resist.

14. (New) The method according to claim 7 wherein said pattern is made of a metal material.

15. (New) The method according to claim 7 wherein said pattern is made of an inorganic material.

16. (New) The method according to claim 7 wherein said insulating film comprises silicon

oxynitride.

17. (New) The method according to claim 7 wherein said insulating film comprises silicon oxide.

18. (New) The method according to claim 7 wherein said insulating film comprises an organic material.

19. (New) The method according to claim 7 wherein said insulating film comprises silicon nitride.

20. (New) The method according to claim 7 wherein said second wiring is a pixel electrode.